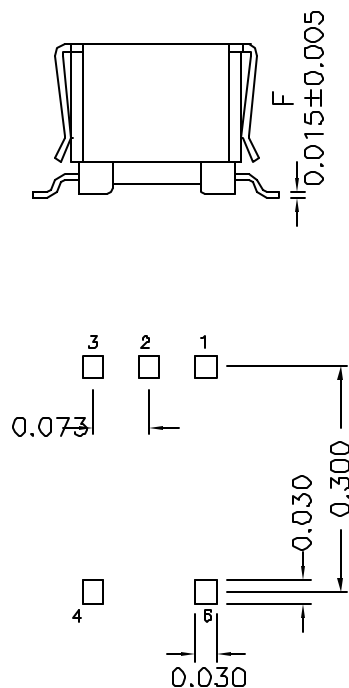
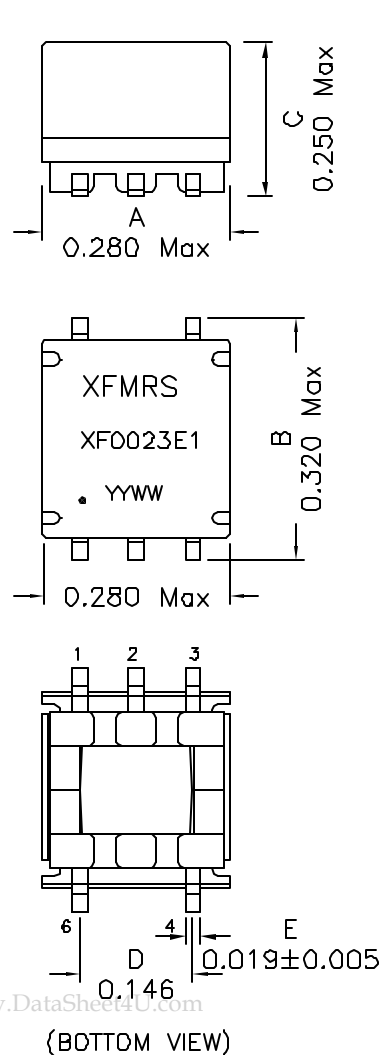


## 1. Mechanical Dimensions:



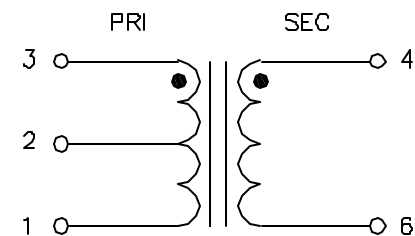
SUGGESTED PAD LAYOUT

### Notes:

1. Solderability: Leads shall meet MIL-STD-202G, Method 208H for solderability.
2. Flammability: UL94V-0
3. ASTM oxygen Index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from -40°C to +85°C
6. Storage Temperature Range: -55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity:  $\pm 0.004^{\circ}$  (0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

DOC REV: A/12

## 2. Schematic:



## 3. Electrical Specifications:

DCL: Pins 3-1 2.0mH Min @10KHz 0.1V

Q: Pins 3-1 TBD Min @10KHz 0.1V

LL: Pins 3-1 1.2uH Max @100KHz 0.1V,  
Short SEC

CW/W: Pins 3-4 50pF Typ @100KHz 0.1V

DCR: Pins 3-1 2.70 Ohms Max

DCR: Pins 4-6 2.60 Ohms Max

LONGITUDINAL BALANCE: 35dB Min @1.544MHz

OPERATION BANDWIDTH: 20KHz-10MHz

RETURN LOSS: 18db Min @50K-3.1MHz

TURNS RATIO: Pins (3-1):(4-6)=1CT:1±1%

HIPOT: 1500Vac, PRI to SEC

<b>XFMRS Inc</b> www.XFMRS.com	Title: T1/E1/ISDN-PRI XFMR			
	UNLESS OTHERWISE SPECIFIED TOLERANCES: .xx ±0.010 Dimensions in Inches		P/N: XF0023E1 DWN. Juan Mao CHK. YK Liao	REV. A Jun-27-08 Jun-27-08
Scale 2.5:1 SHT 1 OF 1	APP.	BW	www.DataSheet4U.com Jun-27-08	